

File No. 14836-9US AD/bns

Montréal, CANADA,

February 29, 2008

UNITED STATES PATENT AND TRADEMARK OFFICE

Application No : 10/532,627
Filing Date : April 25, 2005
Applicant : Microbridge Technologies Inc.
Inventor : Leslie M. Landsberger et al.
Title of Invention : METHOD FOR PRODUCING A PACKAGED INTEGRATED
CIRCUIT
Classification : 2822
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Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

USA

RESPONSE AFTER FINAL

Sir:

In response to the Office Action dated December 13, 2007 in connection with the above-identified Application, please consider the following:

Amendments to the claims begin on page 2 of this paper.

Amendments to the specification begin on page 8 of this paper.

Amendments to the drawings begin on page 11 of this paper.

Remarks begin on page 12 of this paper.

An Appendix including replacement drawing sheets is included after page 13 of this paper.